

# Global 3D IC and 2.5D IC Packaging Market Professional Survey Report 2017

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## Abstracts

### Notes:

Production, means the output of 3D IC and 2.5D IC Packaging

Revenue, means the sales value of 3D IC and 2.5D IC Packaging

This report studies 3D IC and 2.5D IC Packaging in Global market, especially in North America, China, Europe, Southeast Asia, Japan and India, with production, revenue, consumption, import and export in these regions, from 2011 to 2015, and forecast to 2021.

This report focuses on top manufacturers in global market, with production, price, revenue and market share for each manufacturer, covering

Tezzaron

ASE Group

Amkor Technology

STATS ChipPAC Ltd.

By types, the market can be split into

3D wafer-level chip-scale packaging

3D TSV

2.5D

By Application, the market can be split into

Consumer electronics

Telecommunication

Industrial sector

Automotive

Military and aerospace

Smart technologies

Medical devices

By Regions, this report covers (we can add the regions/countries as you want)

North America

China

Europe

Southeast Asia

Japan

India

## Contents

Global 3D IC and 2.5D IC Packaging Market Professional Survey Report 2017

### **1 INDUSTRY OVERVIEW OF 3D IC AND 2.5D IC PACKAGING**

#### 1.1 Definition and Specifications of 3D IC and 2.5D IC Packaging

1.1.1 Definition of 3D IC and 2.5D IC Packaging

1.1.2 Specifications of 3D IC and 2.5D IC Packaging

#### 1.2 Classification of 3D IC and 2.5D IC Packaging

1.2.1 3D wafer-level chip-scale packaging

1.2.2 3D TSV

1.2.3 2.5D

#### 1.3 Applications of 3D IC and 2.5D IC Packaging

1.3.1 Consumer electronics

1.3.2 Telecommunication

1.3.3 Industrial sector

1.3.4 Automotive

1.3.5 Military and aerospace

1.3.6 Smart technologies

1.3.7 Medical devices

#### 1.4 Market Segment by Regions

1.4.1 North America

1.4.2 China

1.4.3 Europe

1.4.4 Southeast Asia

1.4.5 Japan

1.4.6 India

### **2 MANUFACTURING COST STRUCTURE ANALYSIS OF 3D IC AND 2.5D IC PACKAGING**

#### 2.1 Raw Material and Suppliers

#### 2.2 Manufacturing Cost Structure Analysis of 3D IC and 2.5D IC Packaging

#### 2.3 Manufacturing Process Analysis of 3D IC and 2.5D IC Packaging

#### 2.4 Industry Chain Structure of 3D IC and 2.5D IC Packaging

### **3 TECHNICAL DATA AND MANUFACTURING PLANTS ANALYSIS OF 3D IC AND 2.5D IC PACKAGING**

3.1 Capacity and Commercial Production Date of Global 3D IC and 2.5D IC Packaging Major Manufacturers in 2015

3.2 Manufacturing Plants Distribution of Global 3D IC and 2.5D IC Packaging Major Manufacturers in 2015

3.3 R&D Status and Technology Source of Global 3D IC and 2.5D IC Packaging Major Manufacturers in 2015

3.4 Raw Materials Sources Analysis of Global 3D IC and 2.5D IC Packaging Major Manufacturers in 2015

## **4 GLOBAL 3D IC AND 2.5D IC PACKAGING OVERALL MARKET OVERVIEW**

4.1 2011-2016 Overall Market Analysis

4.2 Capacity Analysis

4.2.1 2011-2016 Global 3D IC and 2.5D IC Packaging Capacity and Growth Rate Analysis

4.2.2 2015 3D IC and 2.5D IC Packaging Capacity Analysis (Company Segment)

4.3 Sales Analysis

4.3.1 2011-2016 Global 3D IC and 2.5D IC Packaging Sales and Growth Rate Analysis

4.3.2 2015 3D IC and 2.5D IC Packaging Sales Analysis (Company Segment)

4.4 Sales Price Analysis

4.4.1 2011-2016 Global 3D IC and 2.5D IC Packaging Sales Price

4.4.2 2015 3D IC and 2.5D IC Packaging Sales Price Analysis (Company Segment)

## **5 3D IC AND 2.5D IC PACKAGING REGIONAL MARKET ANALYSIS**

5.1 North America 3D IC and 2.5D IC Packaging Market Analysis

5.1.1 North America 3D IC and 2.5D IC Packaging Market Overview

5.1.2 North America 2011-2016 3D IC and 2.5D IC Packaging Local Supply, Import, Export, Local Consumption Analysis

5.1.3 North America 2011-2016 3D IC and 2.5D IC Packaging Sales Price Analysis

5.1.4 North America 2015 3D IC and 2.5D IC Packaging Market Share Analysis

5.2 China 3D IC and 2.5D IC Packaging Market Analysis

5.2.1 China 3D IC and 2.5D IC Packaging Market Overview

5.2.2 China 2011-2016 3D IC and 2.5D IC Packaging Local Supply, Import, Export, Local Consumption Analysis

5.2.3 China 2011-2016 3D IC and 2.5D IC Packaging Sales Price Analysis

5.2.4 China 2015 3D IC and 2.5D IC Packaging Market Share Analysis

### 5.3 Europe 3D IC and 2.5D IC Packaging Market Analysis

#### 5.3.1 Europe 3D IC and 2.5D IC Packaging Market Overview

#### 5.3.2 Europe 2011-2016 3D IC and 2.5D IC Packaging Local Supply, Import, Export, Local Consumption Analysis

#### 5.3.3 Europe 2011-2016 3D IC and 2.5D IC Packaging Sales Price Analysis

#### 5.3.4 Europe 2015 3D IC and 2.5D IC Packaging Market Share Analysis

### 5.4 Southeast Asia 3D IC and 2.5D IC Packaging Market Analysis

#### 5.4.1 Southeast Asia 3D IC and 2.5D IC Packaging Market Overview

#### 5.4.2 Southeast Asia 2011-2016 3D IC and 2.5D IC Packaging Local Supply, Import, Export, Local Consumption Analysis

#### 5.4.3 Southeast Asia 2011-2016 3D IC and 2.5D IC Packaging Sales Price Analysis

#### 5.4.4 Southeast Asia 2015 3D IC and 2.5D IC Packaging Market Share Analysis

### 5.5 Japan 3D IC and 2.5D IC Packaging Market Analysis

#### 5.5.1 Japan 3D IC and 2.5D IC Packaging Market Overview

#### 5.5.2 Japan 2011-2016 3D IC and 2.5D IC Packaging Local Supply, Import, Export, Local Consumption Analysis

#### 5.5.3 Japan 2011-2016 3D IC and 2.5D IC Packaging Sales Price Analysis

#### 5.5.4 Japan 2015 3D IC and 2.5D IC Packaging Market Share Analysis

### 5.6 India 3D IC and 2.5D IC Packaging Market Analysis

#### 5.6.1 India 3D IC and 2.5D IC Packaging Market Overview

#### 5.6.2 India 2011-2016 3D IC and 2.5D IC Packaging Local Supply, Import, Export, Local Consumption Analysis

#### 5.6.3 India 2011-2016 3D IC and 2.5D IC Packaging Sales Price Analysis

#### 5.6.4 India 2015 3D IC and 2.5D IC Packaging Market Share Analysis

## **6 GLOBAL 2011-2016 3D IC AND 2.5D IC PACKAGING SEGMENT MARKET ANALYSIS (BY TYPE)**

### 6.1 Global 2011-2016 3D IC and 2.5D IC Packaging Sales by Type

### 6.2 Different Types of 3D IC and 2.5D IC Packaging Product Interview Price Analysis

### 6.3 Different Types of 3D IC and 2.5D IC Packaging Product Driving Factors Analysis

#### 6.3.1 3D wafer-level chip-scale packaging of 3D IC and 2.5D IC Packaging Growth Driving Factor Analysis

#### 6.3.2 3D TSV of 3D IC and 2.5D IC Packaging Growth Driving Factor Analysis

#### 6.3.3 2.5D of 3D IC and 2.5D IC Packaging Growth Driving Factor Analysis

## **7 GLOBAL 2011-2016 3D IC AND 2.5D IC PACKAGING SEGMENT MARKET ANALYSIS (BY APPLICATION)**

- 7.1 Global 2011-2016 3D IC and 2.5D IC Packaging Consumption by Application
- 7.2 Different Application of 3D IC and 2.5D IC Packaging Product Interview Price Analysis
- 7.3 Different Application of 3D IC and 2.5D IC Packaging Product Driving Factors Analysis
  - 7.3.1 Consumer electronics of 3D IC and 2.5D IC Packaging Growth Driving Factor Analysis
  - 7.3.2 Telecommunication of 3D IC and 2.5D IC Packaging Growth Driving Factor Analysis
  - 7.3.3 Industrial sector of 3D IC and 2.5D IC Packaging Growth Driving Factor Analysis
  - 7.3.4 Automotive of 3D IC and 2.5D IC Packaging Growth Driving Factor Analysis
  - 7.3.5 Military and aerospace of 3D IC and 2.5D IC Packaging Growth Driving Factor Analysis
  - 7.3.6 Smart technologies of 3D IC and 2.5D IC Packaging Growth Driving Factor Analysis
  - 7.3.7 Medical devices of 3D IC and 2.5D IC Packaging Growth Driving Factor Analysis

## **8 MAJOR MANUFACTURERS ANALYSIS OF 3D IC AND 2.5D IC PACKAGING**

### 8.1 Tezzaron

#### 8.1.1 Company Profile

#### 8.1.2 Product Picture and Specifications

##### 8.1.2.1 3D wafer-level chip-scale packaging

##### 8.1.2.2 3D TSV

##### 8.1.2.3 2.5D

#### 8.1.3 Tezzaron 2015 3D IC and 2.5D IC Packaging Sales, Ex-factory Price, Revenue, Gross Margin Analysis

#### 8.1.4 Tezzaron 2015 3D IC and 2.5D IC Packaging Business Region Distribution Analysis

### 8.2 ASE Group

#### 8.2.1 Company Profile

#### 8.2.2 Product Picture and Specifications

##### 8.2.2.1 3D wafer-level chip-scale packaging

##### 8.2.2.2 3D TSV

##### 8.2.2.3 2.5D

#### 8.2.3 ASE Group 2015 3D IC and 2.5D IC Packaging Sales, Ex-factory Price, Revenue, Gross Margin Analysis

#### 8.2.4 ASE Group 2015 3D IC and 2.5D IC Packaging Business Region Distribution Analysis

### 8.3 Amkor Technology

#### 8.3.1 Company Profile

#### 8.3.2 Product Picture and Specifications

##### 8.3.2.1 3D wafer-level chip-scale packaging

##### 8.3.2.2 3D TSV

##### 8.3.2.3 2.5D

#### 8.3.3 Amkor Technology 2015 3D IC and 2.5D IC Packaging Sales, Ex-factory Price, Revenue, Gross Margin Analysis

#### 8.3.4 Amkor Technology 2015 3D IC and 2.5D IC Packaging Business Region Distribution Analysis

### 8.4 STATS ChipPAC Ltd.

#### 8.4.1 Company Profile

#### 8.4.2 Product Picture and Specifications

##### 8.4.2.1 3D wafer-level chip-scale packaging

##### 8.4.2.2 3D TSV

##### 8.4.2.3 2.5D

#### 8.4.3 STATS ChipPAC Ltd. 2015 3D IC and 2.5D IC Packaging Sales, Ex-factory Price, Revenue, Gross Margin Analysis

#### 8.4.4 STATS ChipPAC Ltd. 2015 3D IC and 2.5D IC Packaging Business Region Distribution Analysis

## **9 DEVELOPMENT TREND OF ANALYSIS OF 3D IC AND 2.5D IC PACKAGING MARKET**

### 9.1 Global 3D IC and 2.5D IC Packaging Market Trend Analysis

#### 9.1.1 Global 2016-2021 3D IC and 2.5D IC Packaging Market Size (Volume and Value) Forecast

#### 9.1.2 Global 2016-2021 3D IC and 2.5D IC Packaging Sales Price Forecast

### 9.2 3D IC and 2.5D IC Packaging Regional Market Trend

#### 9.2.1 North America 2016-2021 3D IC and 2.5D IC Packaging Consumption Forecast

#### 9.2.2 China 2016-2021 3D IC and 2.5D IC Packaging Consumption Forecast

#### 9.2.3 Europe 2016-2021 3D IC and 2.5D IC Packaging Consumption Forecast

#### 9.2.4 Southeast Asia 2016-2021 3D IC and 2.5D IC Packaging Consumption Forecast

#### 9.2.5 Japan 2016-2021 3D IC and 2.5D IC Packaging Consumption Forecast

#### 9.2.6 India 2016-2021 3D IC and 2.5D IC Packaging Consumption Forecast

### 9.3 3D IC and 2.5D IC Packaging Market Trend (Product Type)

### 9.4 3D IC and 2.5D IC Packaging Market Trend (Application)

## **10 3D IC AND 2.5D IC PACKAGING MARKETING TYPE ANALYSIS**

- 10.1 3D IC and 2.5D IC Packaging Regional Marketing Type Analysis
- 10.2 3D IC and 2.5D IC Packaging International Trade Type Analysis
- 10.3 Traders or Distributors with Contact Information of 3D IC and 2.5D IC Packaging by Regions
- 10.4 3D IC and 2.5D IC Packaging Supply Chain Analysis

## **11 CONSUMERS ANALYSIS OF 3D IC AND 2.5D IC PACKAGING**

- 11.1 Consumer 1 Analysis
- 11.2 Consumer 2 Analysis
- 11.3 Consumer 3 Analysis
- 11.4 Consumer 4 Analysis

## **12 CONCLUSION OF THE GLOBAL 3D IC AND 2.5D IC PACKAGING MARKET PROFESSIONAL SURVEY REPORT 2017**

Methodology

Analyst Introduction

Data Source

The report requires updating with new data and is sent in 2-3 business days after order is placed.



## List Of Tables

### LIST OF TABLES AND FIGURES

Figure Picture of 3D IC and 2.5D IC Packaging

Table Product Specifications of 3D IC and 2.5D IC Packaging

Table Classification of 3D IC and 2.5D IC Packaging

Figure Global Production Market Share of 3D IC and 2.5D IC Packaging by Type in 2015

Figure 3D wafer-level chip-scale packaging Picture

Table Major Manufacturers of 3D wafer-level chip-scale packaging

Figure 3D TSV Picture

Table Major Manufacturers of 3D TSV

Figure 2.5D Picture

Table Major Manufacturers of 2.5D

Table Applications of 3D IC and 2.5D IC Packaging

Figure Global Consumption Volume Market Share of 3D IC and 2.5D IC Packaging by Application in 2015

Figure Consumer electronics Examples

Table Major Consumers of Consumer electronics

Figure Telecommunication Examples

Table Major Consumers of Telecommunication

Figure Industrial sector Examples

Table Major Consumers of Industrial sector

Figure Automotive Examples

Table Major Consumers of Automotive

Figure Military and aerospace Examples

Table Major Consumers of Military and aerospace

Figure Smart technologies Examples

Table Major Consumers of Smart technologies

Figure Medical devices Examples

Table Major Consumers of Medical devices

Figure Market Share of 3D IC and 2.5D IC Packaging by Regions

Figure North America 3D IC and 2.5D IC Packaging Market Size (2011-2021)

Figure China 3D IC and 2.5D IC Packaging Market Size (2011-2021)

Figure Europe 3D IC and 2.5D IC Packaging Market Size (2011-2021)

Figure Southeast Asia 3D IC and 2.5D IC Packaging Market Size (2011-2021)

Figure Japan 3D IC and 2.5D IC Packaging Market Size (2011-2021)

Figure India 3D IC and 2.5D IC Packaging Market Size (2011-2021)

Table 3D IC and 2.5D IC Packaging Raw Material and Suppliers  
Table Manufacturing Cost Structure Analysis of 3D IC and 2.5D IC Packaging in 2015  
Figure Manufacturing Process Analysis of 3D IC and 2.5D IC Packaging  
Figure Industry Chain Structure of 3D IC and 2.5D IC Packaging  
Table Capacity and Commercial Production Date of Global 3D IC and 2.5D IC Packaging Major Manufacturers in 2015  
Table Manufacturing Plants Distribution of Global 3D IC and 2.5D IC Packaging Major Manufacturers in 2015  
Table R&D Status and Technology Source of Global 3D IC and 2.5D IC Packaging Major Manufacturers in 2015  
Table Raw Materials Sources Analysis of Global 3D IC and 2.5D IC Packaging Major Manufacturers in 2015  
Table Global Capacity, Sales, Price, Cost, Sales Revenue (M USD) and Gross Margin of 3D IC and 2.5D IC Packaging 2011-2016  
Figure Global 2011-2016 3D IC and 2.5D IC Packaging Market Size (Volume) and Growth Rate  
Figure Global 2011-2016 3D IC and 2.5D IC Packaging Market Size (Value) and Growth Rate  
Table 2011-2016 Global 3D IC and 2.5D IC Packaging Capacity and Growth Rate  
Table 2015 Global 3D IC and 2.5D IC Packaging Capacity List (Company Segment)  
Table 2011-2016 Global 3D IC and 2.5D IC Packaging Sales and Growth Rate  
Table 2015 Global 3D IC and 2.5D IC Packaging Sales List (Company Segment)  
Table 2011-2016 Global 3D IC and 2.5D IC Packaging Sales Price  
Table 2015 Global 3D IC and 2.5D IC Packaging Sales Price List (Company Segment)  
Figure North America Capacity Overview  
Table North America Supply, Import, Export and Consumption of 3D IC and 2.5D IC Packaging 2011-2016  
Figure North America 2011-2016 3D IC and 2.5D IC Packaging Sales Price  
Figure North America 2015 3D IC and 2.5D IC Packaging Sales Market Share  
Figure China Capacity Overview  
Table China Supply, Import, Export and Consumption of 3D IC and 2.5D IC Packaging 2011-2016  
Figure China 2011-2016 3D IC and 2.5D IC Packaging Sales Price  
Figure China 2015 3D IC and 2.5D IC Packaging Sales Market Share  
Figure Europe Capacity Overview  
Table Europe Supply, Import, Export and Consumption of 3D IC and 2.5D IC Packaging 2011-2016  
Figure Europe 2011-2016 3D IC and 2.5D IC Packaging Sales Price  
Figure Europe 2015 3D IC and 2.5D IC Packaging Sales Market Share

Figure Southeast Asia Capacity Overview

Table Southeast Asia Supply, Import, Export and Consumption of 3D IC and 2.5D IC Packaging 2011-2016

Figure Southeast Asia 2011-2016 3D IC and 2.5D IC Packaging Sales Price

Figure Southeast Asia 2015 3D IC and 2.5D IC Packaging Sales Market Share

Figure Japan Capacity Overview

Table Japan Supply, Import, Export and Consumption of 3D IC and 2.5D IC Packaging 2011-2016

Figure Japan 2011-2016 3D IC and 2.5D IC Packaging Sales Price

Figure Japan 2015 3D IC and 2.5D IC Packaging Sales Market Share

Figure India Capacity Overview

Table India Supply, Import, Export and Consumption of 3D IC and 2.5D IC Packaging 2011-2016

Figure India 2011-2016 3D IC and 2.5D IC Packaging Sales Price

Figure India 2015 3D IC and 2.5D IC Packaging Sales Market Share

Table Global 2011-2016 3D IC and 2.5D IC Packaging Sales by Type

Table Different Types 3D IC and 2.5D IC Packaging Product Interview Price

Table Global 2011-2016 3D IC and 2.5D IC Packaging Sales by Application

Table Different Application 3D IC and 2.5D IC Packaging Product Interview Price

Table Tezzaron Information List

Table 3D wafer-level chip-scale packaging 3D IC and 2.5D IC Packaging Overview

Table 3D TSV 3D IC and 2.5D IC Packaging Overview

Table 2015 Tezzaron 3D IC and 2.5D IC Packaging Revenue, Sales, Ex-factory Price

Figure 2015 Tezzaron 2015 3D IC and 2.5D IC Packaging Business Region Distribution

Table ASE Group Information List

Table 3D wafer-level chip-scale packaging 3D IC and 2.5D IC Packaging Overview

Table 3D TSV 3D IC and 2.5D IC Packaging Overview

Table 2015 ASE Group 3D IC and 2.5D IC Packaging Revenue, Sales, Ex-factory Price

Figure 2015 ASE Group 2015 3D IC and 2.5D IC Packaging Business Region Distribution

Table Amkor Technology Information List

Table 3D wafer-level chip-scale packaging 3D IC and 2.5D IC Packaging Overview

Table 3D TSV 3D IC and 2.5D IC Packaging Overview

Table 2015 Amkor Technology 3D IC and 2.5D IC Packaging Revenue, Sales, Ex-factory Price

Figure 2015 Amkor Technology 2015 3D IC and 2.5D IC Packaging Business Region Distribution

Table STATS ChipPAC Ltd. Information List

Table 3D wafer-level chip-scale packaging 3D IC and 2.5D IC Packaging Overview

Table 3D TSV 3D IC and 2.5D IC Packaging Overview

Table 2015 STATS ChipPAC Ltd. 3D IC and 2.5D IC Packaging Revenue, Sales, Ex-factory Price

Figure 2015 STATS ChipPAC Ltd. 2015 3D IC and 2.5D IC Packaging Business Region Distribution

Figure Global 2016-2021 3D IC and 2.5D IC Packaging Market Size (Volume) and Growth Rate Forecast

Figure Global 2016-2021 3D IC and 2.5D IC Packaging Market Size (Value) and Growth Rate Forecast

Figure Global 2016-2021 3D IC and 2.5D IC Packaging Sales Price Forecast

Figure North America 2016-2021 3D IC and 2.5D IC Packaging Consumption Volume and Growth Rate Forecast

Figure China 2016-2021 3D IC and 2.5D IC Packaging Consumption Volume and Growth Rate Forecast

Figure Europe 2016-2021 3D IC and 2.5D IC Packaging Consumption Volume and Growth Rate Forecast

Figure Southeast Asia 2016-2021 3D IC and 2.5D IC Packaging Consumption Volume and Growth Rate Forecast

Figure Japan 2016-2021 3D IC and 2.5D IC Packaging Consumption Volume and Growth Rate Forecast

Figure India 2016-2021 3D IC and 2.5D IC Packaging Consumption Volume and Growth Rate Forecast

Table Global Sales Volume of 3D IC and 2.5D IC Packaging by Types 2016-2021

Table Global Consumption Volume of 3D IC and 2.5D IC Packaging by Applications 2016-2021

Table Traders or Distributors with Contact Information of 3D IC and 2.5D IC Packaging by Regions

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